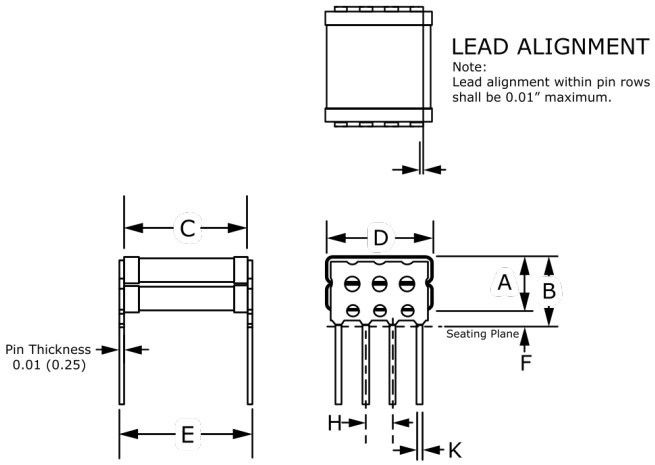
L1GN40D124JH02

KPS-MCC Indust C0G HT200C, Ceramic, 0.12 uF, 5%, 1000 VDC, C0G



Click here for the 3D model.

Dimensions

D	10.16mm +/-0.635mm
L	6.35mm MIN
H	2.54mm NOM
F	1.397mm +/-0.25mm
A	5.3mm MAX
B	7.078mm MAX
C	10.16mm +/-0.635mm
E	11.18mm MAX
K	0.5mm NOM

Packaging Specifications

Packaging	Waffle, Box
Packaging Quantity	50

General Information

Series	KPS-MCC Indust C0G HT200C
Style	Leaded Stacked Chip
Description	Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	No
Prop 65	⚠ **WARNING:** Cancer and reproductive harm - http://www.p65warnings.ca.gov.
SCIP Number	89f79324-98a2-425d-914d-1725e977d89a
Termination	60/40 Solder Coated
Lead	Straight Leads
AEC-Q200	No
Notes	Number of chips in this stack: 2.

Specifications

Capacitance	0.12 uF
Capacitance Tolerance	5%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1200 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	C0G
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	8.33 GOhms